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**Product
Bulletin**

E-625

**MICROSORB E-625
Low Density Potting Compound**

MICROSORB E-625 is a one-part epoxy based potting compound. It is a low-viscosity makes it suitable for dispensing machines.

Typical applications for **MICROSORB E-625** include insert bonding, edge filling of honeycomb and applications requiring a low-density dielectric material.

MICROSORB E-625 one-part chemistry exhibits minimal exotherm when cured at 250°F or 350°F. It's service temperature is -67°F to 350°F.

SPECIFICATIONS

Color: White
 Density, Cured, lbs/ft³: 25 – 31
 Form: Low-viscosity, thixotropic paste
 Slump: ≤ 0.01"
 Shelf Life: 6 Months @ 0°F or Below
 Working Time, @ 75°F: 15 Days

MECHANICAL PROPERTIES

Compression Strength

| Cure Temperature | Test Temperature | Density | Compression Strength, psi |
|------------------|------------------|------------------------|---------------------------|
| 350°F | 75°F | 28 lbs/ft ³ | 3,000 |
| 350°F | 75°F | 28 lbs/ft ³ | 3,100 |

Shear Strength

| Cure Temperature | 75°F | 180 °F | 250°F |
|------------------|-------|--------|-------|
| 250°F | 1,000 | 1,200 | 270 |
| 350°F | 1,200 | 1,300 | 300 |

INSTRUCTIONS FOR USE

Some filler settling is common. We recommend the shipping container be thoroughly mixed prior to use. Power mixing is preferred.

Pour out the amount of E-625 to be used.

Heat to 150°F (65°C) to reduce viscosity.

Evacuate to ensure air a void free casting.

Pour into mold or cavity.

Cure with a ramp temperature, steps of 5°F rate to 250°F or 350°F, and hold for 60 minutes.

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